



## Direct-attached storage products with large capacity and high performance

Huawei OceanStor V3 DAS is a storage product for direct-attached storage applications. It provides customers with enterprise-class DAS solutions featuring solid reliability, elastic scalability, and great cost effectiveness. With a dual-channel, fully redundant, and high-density architecture, the OceanStor V3 DAS employs modules and 12 Gbit/s SAS interconnection technology to yield industry-leading ease of use, reliability, and efficiency. It can satisfy DAS needs in cloud computing, virtualization, HPC, backup, archive, and other scenarios while maximizing server storage capacity. This design helps customers easily meet ever-increasing data storage demands.

## Features



### Flexible and Reliable

- Modular component design reduces costs and complexities of conventional storage architecture and satisfies capacity needs now and well into the future.
- Hot-swappable components enable non-disruptive device replacement and capacity expansion while improving reliability and simplifying maintenance.
- Fully redundant expansion, fan, and power modules eliminate single points of failure and provide high-level redundancy and reliability.



### Scalable

- Large-capacity disks (10 TB) in a 4 U high-density disk enclosure (accommodating up to 75 disks) deliver great affordability.
- One common disk enclosure can be connected to up to seven disk enclosures and accommodate a maximum of 192 disks in total, supporting up to 1920 TB of capacity. This fully fulfills large-capacity needs.
- One high-density disk enclosure can be connected to up to seven disk enclosures and accommodate a maximum of 600 disks in total, supporting up to 6000 TB of capacity. This affords users super-large capacity.



### Economic and Efficient

- A high-density disk enclosure stores three times as much data in the same amount of space, greatly improving rack space utilization. Best price per TB allows users to use super-high density storage capacity.
- Disks in a high-density disk enclosure are more energy-efficient than those in a common disk enclosure, significantly reducing power consumption.
- New-generation high-speed interconnection technology and 12 Gbit/s SAS transmission protocol ensure data transferred between services at a high speed.

## Technical Specifications

Model	DAS32525U2	DAS32435U4	DAS37535U4
<b>Hardware Specifications</b>			
Enclosure height	2 U	4 U	4 U
Maximum number of cascaded enclosures	8	8	8
Maximum capacity	180 TB	1920 TB	6000 TB
Disks per enclosure	25	24	75
Disk type	2.5-inch SAS SSD:900GB/960GB 2.5-inch SAS HDD: 1.2TB	3.5-inch NL-SAS HDD: 4TB/6TB/8TB/10TB	3.5-inch SAS SSD:600GB (only 15 disks in row A) 3.5-inch NL-SAS HDD: 4TB/6TB/8TB/10TB
Port type	12 Gbit/s SAS		
<b>Compatibility</b>			
HBA	LSI 9300-8e LSI 9200-8e LSI 9380-8e(manage software version 16.11.00.03 or later)		
Operating system	Red Hat Enterprise Linux 6 Server X86 64 (update 8 or later) 64-bit version of CentOS 7 (update 2 or later) Microsoft Windows Server 2008 R2 (SP1) Microsoft Windows Server 2012 R2 (SP2)		
<b>Physical Specifications</b>			
Power supply	AC: 100 V to 240 V, DC: 192V to 288V	AC: 100 V to 240 V, DC: 192V to 288V	AC: 100 V to 240 V, DC: -48V to -60V
Maximum power consumption	354 W	500 W	1008 W
Dimensions (D x W x H)	86.1 mm × 447 mm × 488 mm	175 mm × 447 mm × 488 mm	176.5 mm x 446 mm x 790 mm
Weight	17.5 kg (empty)	26.5 kg (empty)	48 kg (empty)
Operating temperature	The ambient temperature is from 5°C to 40°C, at an altitude lower than 1800 m. The ambient temperature decreases by 1°C every time the altitude increases by 220 m, at an altitude ranging from 1800 m to 3000 m.		The ambient temperature is from 5°C to 35°C, at an altitude lower than 1800 m. The ambient temperature decreases by 1°C every time the altitude increases by 220 m, at an altitude ranging from 1800 m to 3000 m.
Operating humidity	10% RH to 90% RH		

### For More Information

To learn more about Huawei storage, please contact the local office or visit Huawei Enterprise website <http://e.huawei.com>.



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